

ABSTRACT

Disclosed is a conductive connecting material 30 used to form conductive portions on a plurality of terminals 11 of an electronic member having a substrate 10 and the plurality of terminals 11 provided on the substrate 10, comprising a metal layer 110 and a resin layer 120 having a resin component and a filler, in which the metal layer is aggregated on each of terminals to form the conductive portions on the plurality of terminals by bringing the conductive connecting material into contact with the plurality of terminals and heating the conductive connecting material.